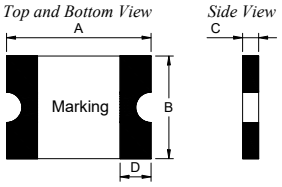
1、Physical Dimensions(size of 1210)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
K1210L200/8AR	3.00	3.43	2.35	2.80	0.60	1.00	0.30	T20



2、Electrical Characteristics

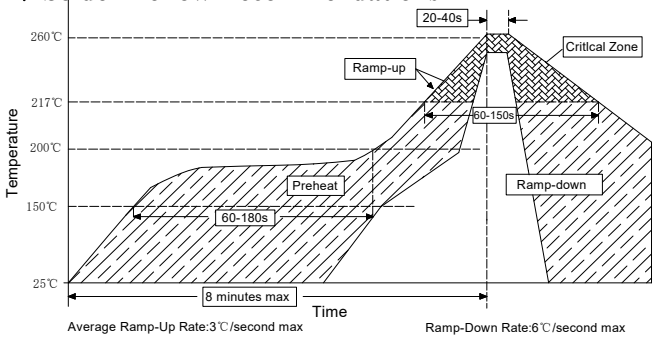
Part Number	I_H (A)	I_T (A)	V_{max} (V)	I_{max} (A)	T_{trip} (Max time to trip)		Pd_{typ} （W）	R_{min} (Ω)	$R1_{max}$ (Ω)
					Current(A)	Time(S)			
K1210L200/8AR	2.00	4.00	8	40	8.00	1.00	0.70	0.02	0.09

I_H: Holding Current: maximum current at which the device will not trip in 25℃ still air.
I_T: Tripping Current minimum current at which the device will trip in 25℃ still air.
V_{max}: Maximum voltage device can withstand without damage at rated current.
I_{max}: Maximum fault current device can withstand without damage at rated voltage.
T_{trip}: Maximum time to trip(s) at assigned current.
Pd_{typ}: Rated working power.
R_{min}: Minimum resistance of device prior to trip at 25℃.
$R1_{max}$: Maximum resistance of device is measured one hours post reflow at 25℃.
Noted: All electrical function test is conducted after PCB mounted.

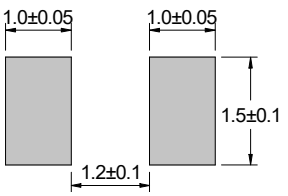
3、Thermal Derating

K1210L200/8AR	Maximum ambient operating temperature								
	-40℃	-20℃	0℃	25℃	40℃	50℃	60℃	70℃	85℃
Hold Current(A)	3.20	2.80	2.40	2.00	1.80	1.60	1.40	1.20	1.00
Trip Current(A)	6.40	5.60	4.80	4.00	3.60	3.20	2.80	2.40	2.00

4、Solder Reflow Recommendations



Recommended Pad Layout(mm)



Notes:If reflow temperatures exceed the recommended profile,devices may not meet the performance requirements.

5、Package Information

Packing quantity:3500PCS/Reel

Note:Reel packaging per EIA-481-1 standard